

## Performance level 3 as per IEC 60 603-2

50 mating cycles then visual inspection.  
No gas test.  
No functional impairment.

Part No. explanation **09** . . . . . **7 . . . .**

## Performance level 2 as per IEC 60 603-2

400 mating cycles. then 4 days gas test using 10 ppm SO<sub>2</sub>.  
200 mating cycles. Measurement of contact resistance.  
200 mating cycles. then visual inspection. No abrasion of the contact finish through to the base material.  
No functional impairment.

Part No. explanation **09** . . . . . **6 . . . .**

## Performance level 1 as per IEC 60 603-2

500 mating cycles. then 10 days gas test using 10 ppm SO<sub>2</sub>.  
250 mating cycles. Measurement of contact resistance.  
250 mating cycles. then visual inspection. No abrasion of the contact finish through to the base material.  
No functional impairment.

Part No. explanation **09** . . . . . **2 . . . .**

## Performance level 2 as per IEC 61 076-4-113

250 mating cycles. then 4 days gas test using 10 ppm SO<sub>2</sub>.  
125 mating cycles. Measurement of contact resistance.  
125 mating cycles. then visual inspection. No abrasion of the contact finish through to the base material.  
No functional impairment.

Part No. explanation **02** . . . . . **2 . . . .**

## Performance level 1 as per IEC 61 076-4-113

500 mating cycles. then 10 days gas test using 10 ppm SO<sub>2</sub>.  
250 mating cycles. Measurement of contact resistance.  
250 mating cycles. then visual inspection. No abrasion of the contact finish through to the base material.  
No functional impairment.

Part No. explanation **02** . . . . . **1 . . . .**

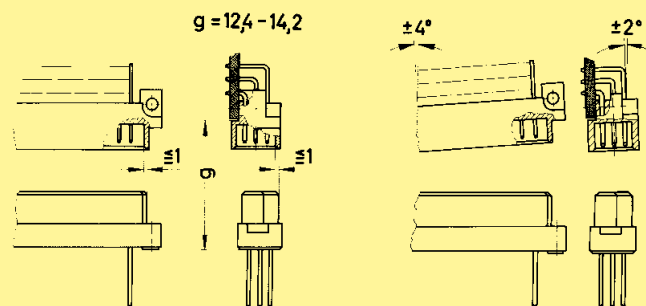
Other plating finishes available on request.

## Mating conditions

To ensure reliable connections and prevent unnecessary damage, please refer to the application data diagrams.

These recommendations are set out in IEC 60 603-2.

The connectors should not be coupled and decoupled under electrical load.



## Soldering the male connectors into pcb's

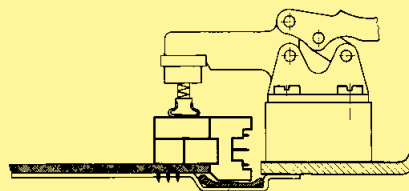
Male connectors should be protected when being soldered in a dip, flow or film soldering baths. Otherwise, they might become contaminated as a result of soldering operations or deformed as a result of overheating.

- ① For prototypes and short runs protect the connectors with an industrial adhesive tape, e.g. Tesaband 4331 ([www.tesa.de](http://www.tesa.de)). Cover the underside of the connector moulding and the adjacent parts of the pcb as well as the open sides of the connector. This will prevent heat and gases of the soldering apparatus from damaging the connector. About 140 + 5 mm of the tape should suffice.
- ② For large series a jig is recommended. Its protective cover with a fast action mechanical locking device shields the connectors from gas and heat generated by the soldering apparatus. As an additional protection a foil can be used for covering the parts that should not be soldered.
- ③ For prototypes and short runs the protection described under point ① can be replaced by a solder protection cap. This cap can be ordered under the part no. 09 02 000 9935.

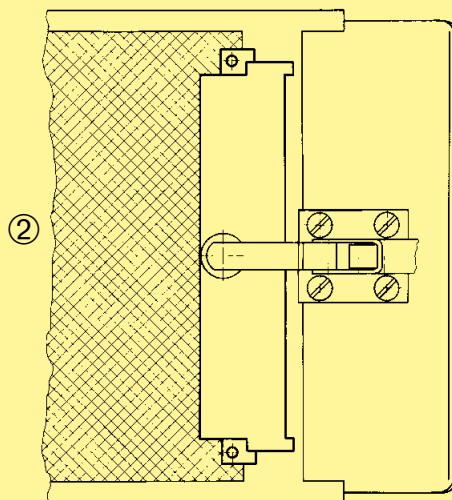


Adhesive tape or protection cap

① + ③



Intermediate foil



②